

SPECIFICATION

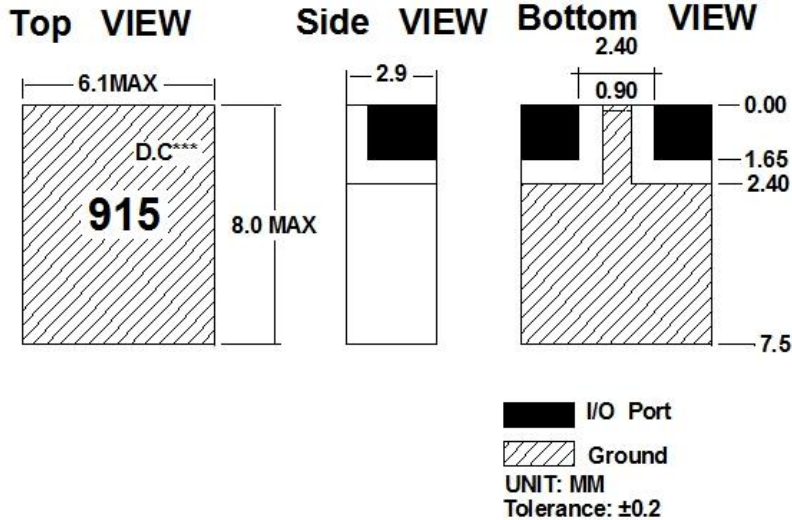
Part No.: _____
 Customer: _____
 Date: 2017.02.21

Written by	Checked by	Approval
FL Lai	PH Jiang	CK Chang

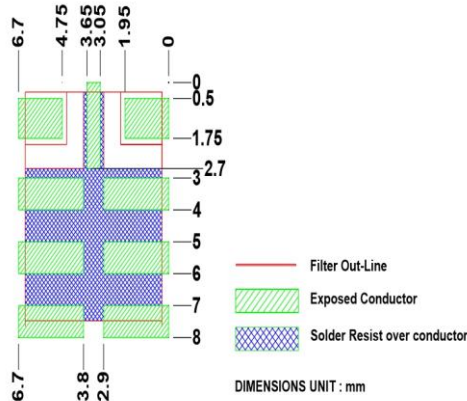
ELECTRICAL SPECIFICATIONS

ITEM	SPEC	UNIT
1	Center freq	915.0
2	Bandwidth [1dB BW]	$f_o \pm 13.0$ [902.0~928.0]
3	Insertion Loss in BW	2.5
4	Ripple in BW	1.0
5	Return Loss in BW	
6	V S W R in BW	2.0
7	Attenuation (Absolute Value)	23 dB min. @ $f_o \pm$ [837.5 &] 26 dB min. @ $f_o \pm$ [992.5 &]
8	Group Delay Variation	
9	Input Power	2.0
10	In/Out Impedance	50Ω
11	Operation Temperature Range	-30°C to +85°C

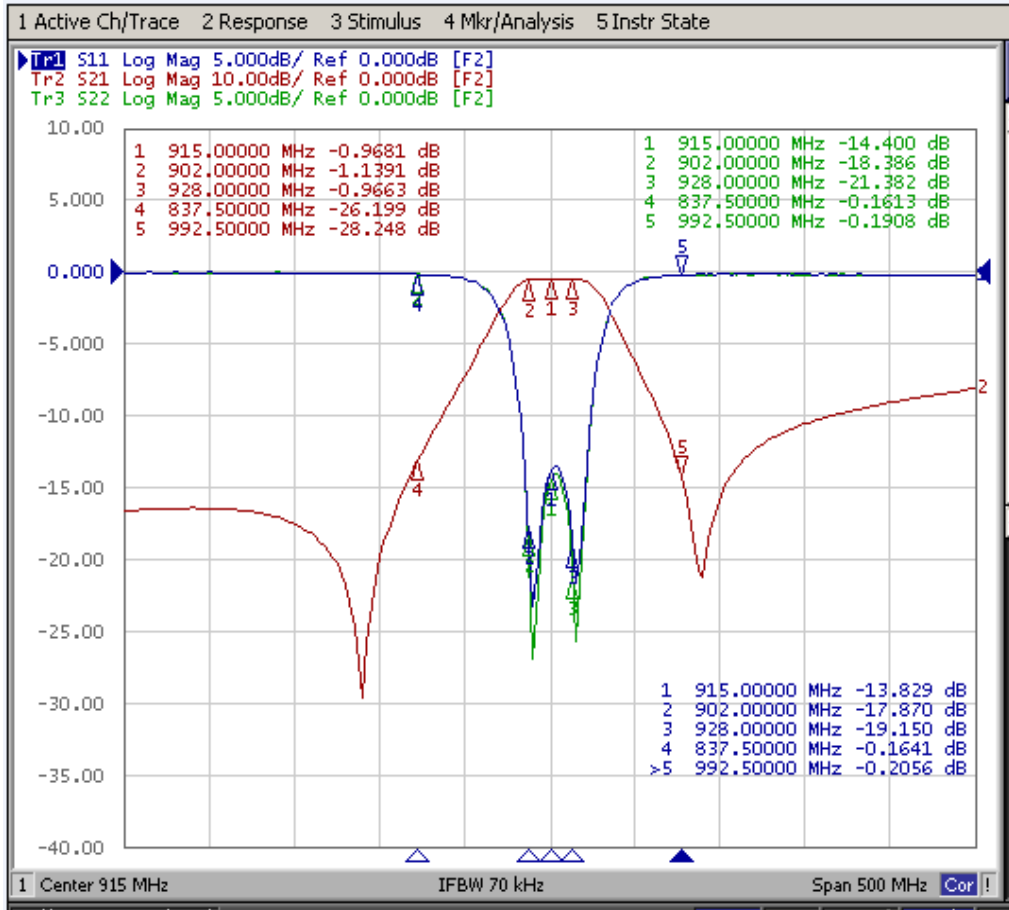
MECHANICAL SPECIFICATIONS



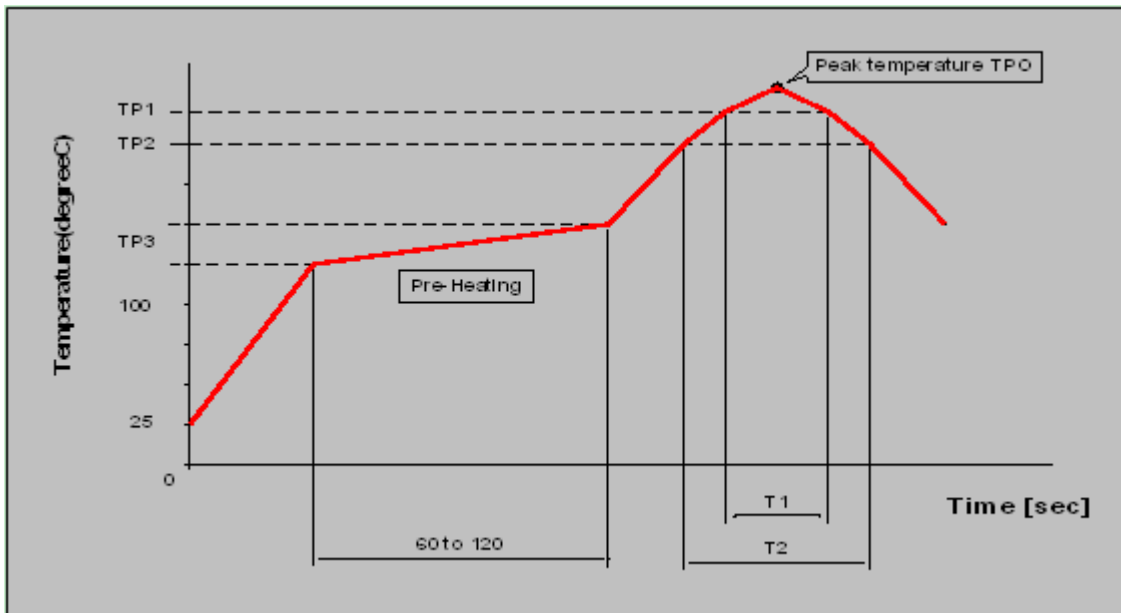
RECOMMENDED PC BOARD PATTERN



PERFORMANCE



SOLDERING CONDITION



Measuring point of temperature : IN-OUT Terminals of The Device

Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

Reflow standard condition	TPO (°C)	TP1 (°C)	T1 (s)	TP2 (°C)	T2 (s)	TP3 (°C)
Sn-3Ag-0.5 solder	245+/-5	220	30 to 60	—	—	150 to 180
Test condition of reflow teat resistance	260+5/-0	240	20	220	70	150 to 180